

RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

# **Data Sheet**

## SAW WLAN filter

Series/type: B8873

Ordering code: B39242B8873P810

Date: Dec 12, 2018

Version: 2.1

DCN: 80-PA243-261 Rev. B

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").

RF360 Holdings Singapore Pte. Ltd. is a joint venture of Qualcomm Global Trading Pte. Ltd. and EPCOS AG.

RF360 Europe GmbH, Anzinger Str. 13, München, Germany



These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.



## RF360 Europe GmbH A Qualcomm – TDK Joint Venture

## **Table of contents**

/
5
6
7
8
10
11
15
16
17
18
19



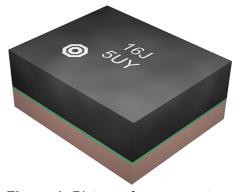
## RF360 Europe GmbH A Qualcomm – TDK Joint Venture

#### 1 Application

- Ultra low-loss RF single filter for WLAN with LTE Band 7/ Band 40/ Band 41 coexistence
- Usable passband: 79.0 MHz
- Filter impedance 50  $\Omega$

#### 2 Features

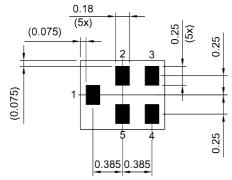
- RoHS compatible
- Package size 1.1 mm × 0.9 mm
- Package height 0.45 mm (max.)
- Approximate weight 1 mg
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)



**Figure 1:** Picture of component with example of product marking.

### 3 Package

**BOTTOM VIEW** 



Pad and pitch tolerance ±0.05

## 4 Pin configuration

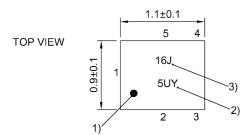
■ 1 Input

■ 4 Output

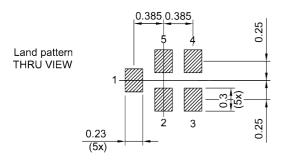
■ 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

## 5 Matching circuit

■  $L_{p1}$  = 6.2 nH

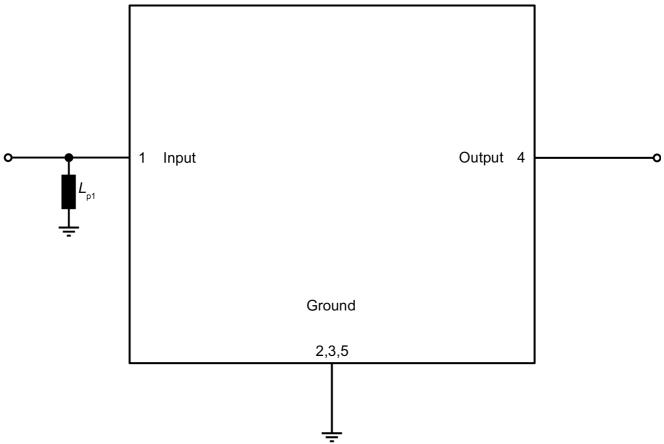


Figure 3: Schematic of matching circuit.



#### 6 Characteristics

Temperature range for specification  $T_{\rm SPEC} = -20~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C}$ Input terminating impedance  $Z_{\rm IN} = 50~\Omega$  with par. 6.2 nH<sup>1)</sup>

Output terminating impedance  $Z_{\text{OUT}} = 50 \,\Omega$ 

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	2442	_	MHz
Insertion Loss			α				
WiFi CH 1	2403.1 2420.9	MHz		_	1.2 <sup>2)</sup>	1.8 <sup>2)</sup>	dB
WiFi CH 2	2408.1 2425.9	MHz		_	1.0 <sup>2)</sup>	1.5 <sup>2)</sup>	dB
WiFi CH 3 – CH 11	2413.1 2470.9	MHz		_	0.92)	1.6 <sup>2)</sup>	dB
WiFi CH 12	2458.1 2475.9	MHz		_	1.1 <sup>2)</sup>	2.02)	dB
WiFi CH 13	2463.1 2480.9	MHz		_	1.3 <sup>2)</sup>	2.03)	dB
Amplitude ripple (p-p)			Δα				
WiFi CH 1	2403.1 2420.9	MHz		_	0.7	1.5	dB
WiFi CH 2	2408.1 2425.9	MHz		_	0.7	1.1	dB
WiFi CH 3 – CH 11	2413.1 2470.9	MHz		_	0.66)	1.2 <sup>6)</sup>	dB
WiFi CH 12	2458.1 2475.9	MHz		_	0.8	2.0	dB
WiFi CH 13	2463.1 2480.9	MHz		_	1.0	3.27)	dB
VSWR			VSWR				
input port @ CH 1 – CH 13	2403.1 2480.9	MHz		_	1.6	2.2	
output port @ CH 1 - CH 13	2403.1 2480.9	MHz		_	1.6	2.2	
Attenuation			α				
	700 960	MHz		31	35	_	dB
	1700 2000	MHz		26	29	_	dB
	2300 2370	MHz		274)	374)	_	dB
	2370 2380	MHz		64)	334)	_	dB
	2496 2501	MHz		16 <sup>5)</sup>	284)	_	dB
	2500 2505	MHz		32 <sup>5)</sup>	404)	_	dB
	2505 2570	MHz		304)	404)	_	dB
	2570 2620	MHz		29	33	_	dB
	2620 2690	MHz		27	31	_	dB
	4800 5805	MHz		27	31	_	dB

See Sec. Matching circuit (p. 6).

<sup>2)</sup> Average over each WLAN channel with bandwidth of 17.8 MHz

Average over each WLAN channel with bandwidth of 17.8 MHz; Valid for temp  $T = -20^{\circ}C$  to 65°C

<sup>4)</sup> Average over any 5.0 MHz

<sup>5)</sup> Average over any 5.0 MHz; Valid for temp T = 25°C to 85°C

<sup>6)</sup> Within any 17.8Mhz

<sup>7)</sup> Valid for temp T = -20°C to 65°C



## 7 Maximum ratings

Storage temperature	$T_{\text{STG}}^{2)} = -40 ^{\circ}\text{C} \dots +85 ^{\circ}\text{C}^{1)}$	
DC voltage	$ V_{DC}  = 3.0 \text{ V (max.)}^{3)}$	
ESD voltage	$V_{\rm ESD}^{4)} = 50  \text{V (max.)}$	Machine model.
Power @ input port: Channel 1 to Channel 13	P <sub>IN</sub> = 24 dBm	19 MHz WLAN signal for 5000 h @ 55 °C.

<sup>1)</sup> Extended upperlimit: 96h@125°C acc. to IEC 60068-2-2 Bb.

<sup>2)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>&</sup>lt;sup>3)</sup> 168h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

<sup>&</sup>lt;sup>4)</sup> According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

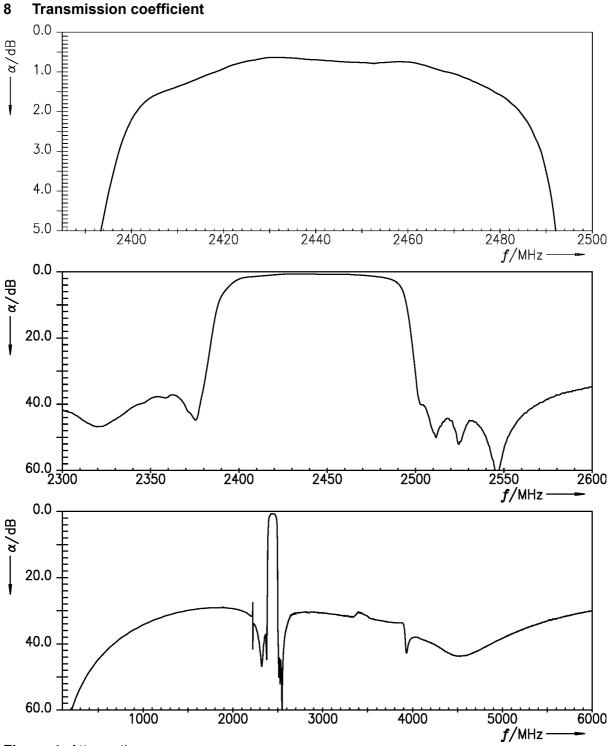
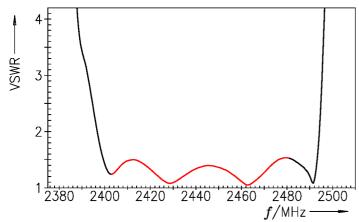


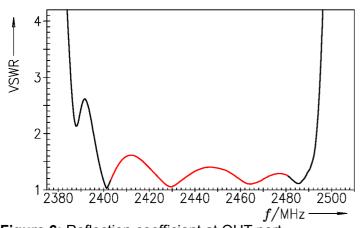
Figure 4: Attenuation.

#### 9 Reflection coefficients



 $Z_{\text{IN}}=50 \Omega$ 

Figure 5: Reflection coefficient at IN port.



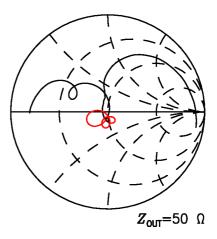
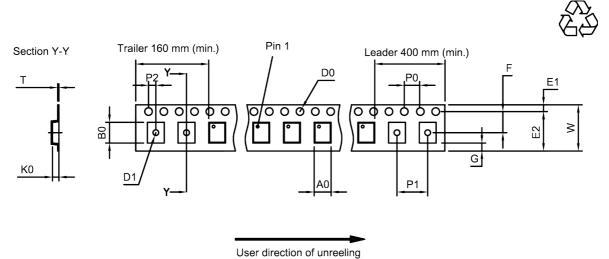


Figure 6: Reflection coefficient at OUT port.

## 10 Packing material

## 10.1 Tape



**Figure 7:** Drawing of tape (first-angle projection) is for illustration only and not to scale. Tape Dimensions in Table 1 are the valid dimensions for the tape.

A <sub>0</sub>	1.02±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	2.0±0.1 mm
B <sub>0</sub>	1.22±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
$D_0$	1.55±0.05 mm	G	_	Т	0.25±0.03 mm
D <sub>1</sub>	0.55±0.1 mm	$K_0$	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75 <sub>±0.1</sub> mm	P <sub>0</sub>	4.0±0.1 mm		

**Table 1:** Tape dimensions.

#### 10.2 Reel with diameter of 180 mm

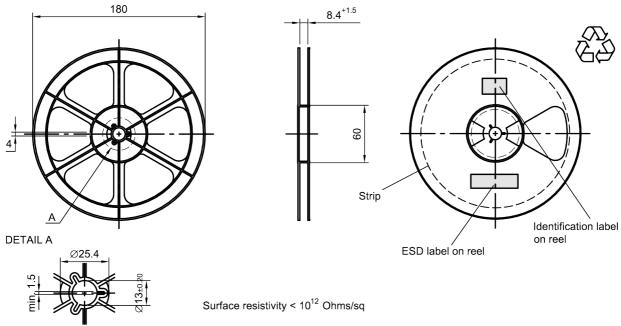


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

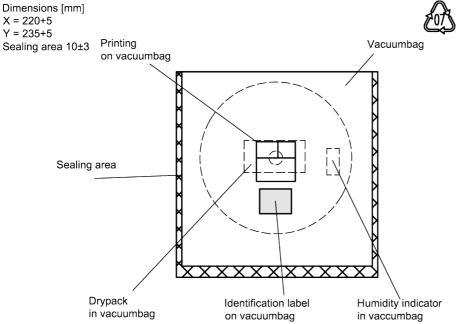


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

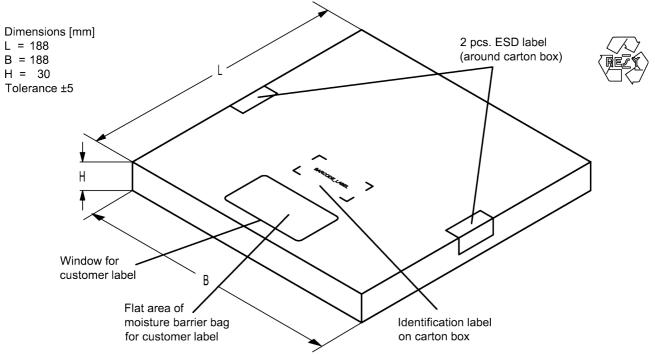


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

#### 10.3 Reel with diameter of 330 mm

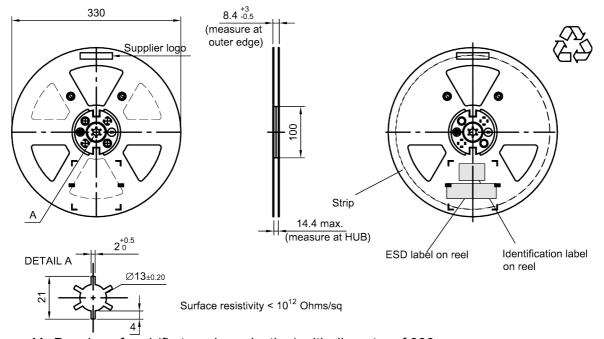


Figure 11: Drawing of reel (first-angle projection) with diameter of 330 mm.

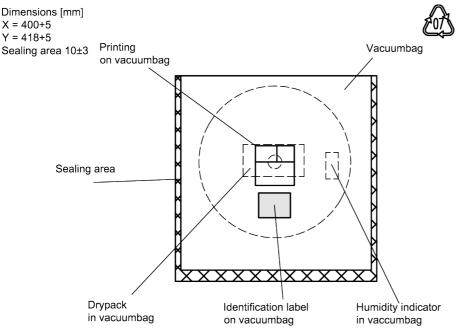


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

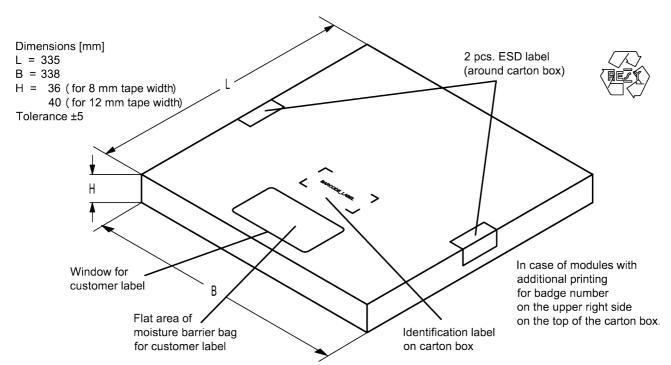


Figure 13: Drawing of folding box for reel with diameter of 330 mm.

#### 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

#### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B8873 is 8N9.

#### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345  $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	M	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	X	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	X	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E 38		r	
15	F	39	t	
16	G	40	V	
17	H 41		\	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	М	45	<	
22	N	46	>	
23	Р			

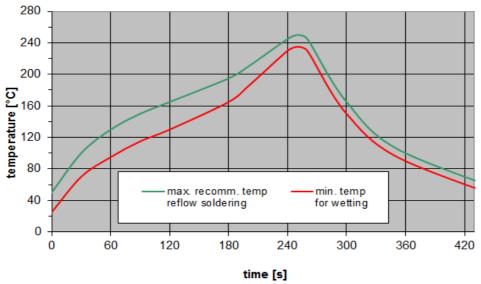
Table 2: Lists for encoding and decoding of marking.

## 12 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

≤ 3 K/s
125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
30 s to 70 s
min. 10 s
max. 20 s
-
250 °C +0/-5 °C
230 °C +5/-0 °C for 10 s ± 1 s
≤ 3 K/s
measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.



#### 13 Annotations

#### 13.1 Matching coils

See TDK inductor pdf-catalog <a href="http://www.tdk.co.jp/tefe02/coil.htm#aname1">http://www.tdk.co.jp/tefe02/coil.htm#aname1</a> and Data Library for circuit simulation <a href="http://www.tdk.co.jp/etvcl/index.htm">http://www.tdk.co.jp/etvcl/index.htm</a>.

## 13.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

#### 13.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

#### 13.4 Ordering codes and packing units

Ordering code	Packing unit
B39242B8873P810	15,000 pcs
B39242B8873P810S 5	5,000 pcs

Table 4: Ordering codes and packing units.



#### 14 Cautions and warnings

#### 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.rf360jv.com/orderingcodes">www.rf360jv.com/orderingcodes</a>.

#### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

#### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

#### 14.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



#### 15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (<a href="www.rf360jv.com/material">www.rf360jv.com/material</a>). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.

The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Qualcomm RF360: B39242B8873P810